

**SB1045L**

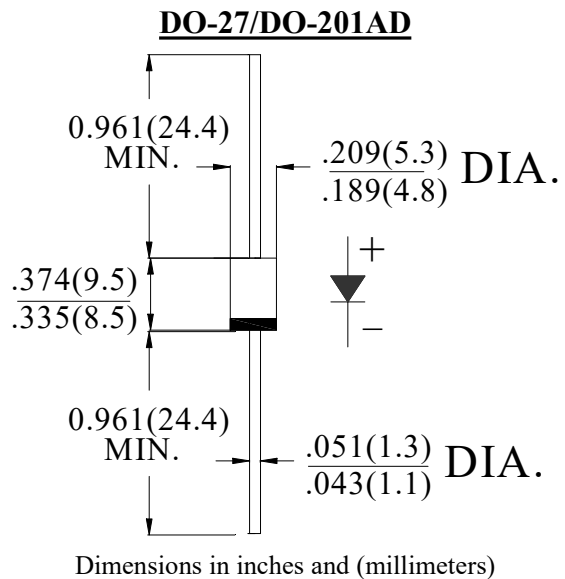
**10.0AMPS. SCHOTTKY BARRIER RECTIFIERS**

**FEATURE**

- . High current capability
- . Low forward voltage drop
- . Low power loss, high efficiency
- . High surge capability
- . High temperature soldering guaranteed  
260°C /10sec/0.375" lead length at 5 lbs tension

**MECHANICAL DATA**

- . Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C
- . Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy ( free halogen )
- . Polarity: color band denotes cathode
- . Mounting position: any



**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYM BOL	SB1045L	units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	45	V
Maximum RMS Voltage	$V_{RMS}$	31.5	V
Maximum DC blocking Voltage	$V_{DC}$	45	V
Maximum Average Forward Rectified Current .375"(9.5mm) lead length	$I_{F(AV)}$	10.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	150.0	A
Maximum Forward Voltage	@ $I_F=2A$	0.33	V
	@ $I_F=10A$	0.45	
Maximum DC Reverse Current at rated DC blocking voltage	@ $T_J=25^{\circ}C$	0.2	mA
	@ $T_J=100^{\circ}C$	20.0	
Typical Junction Capacitance(Note1)	$C_J$	600	pF
Typical Thermal Resistance(Note2)	$R_{(JA)}$	40	°C/W
Storage Temperature	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature	$T_J$	-55 to +125	°C

**Note:**

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
2. Thermal Resistance from Junction to Ambient and Lead at 0.375"(9.5mm) lead length, vertical P.C. Board Mounted

**RATING AND CHARACTERISTIC CURVES**

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

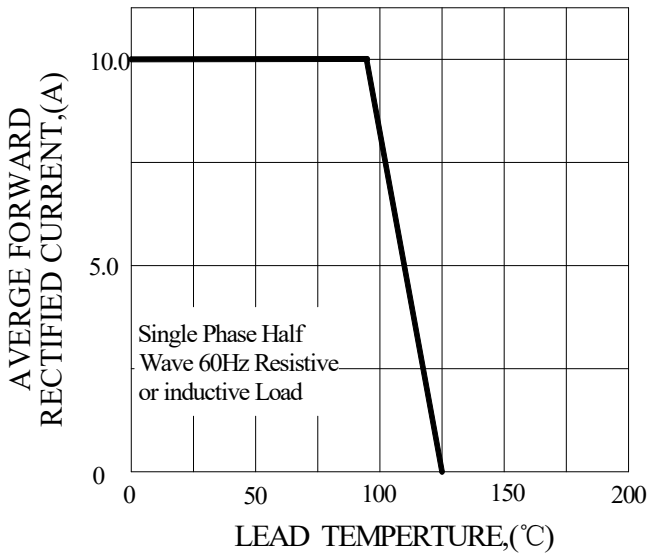


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

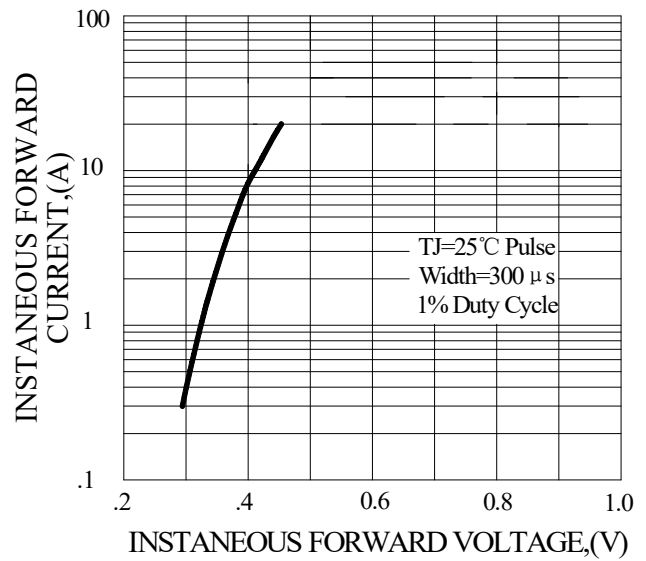


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

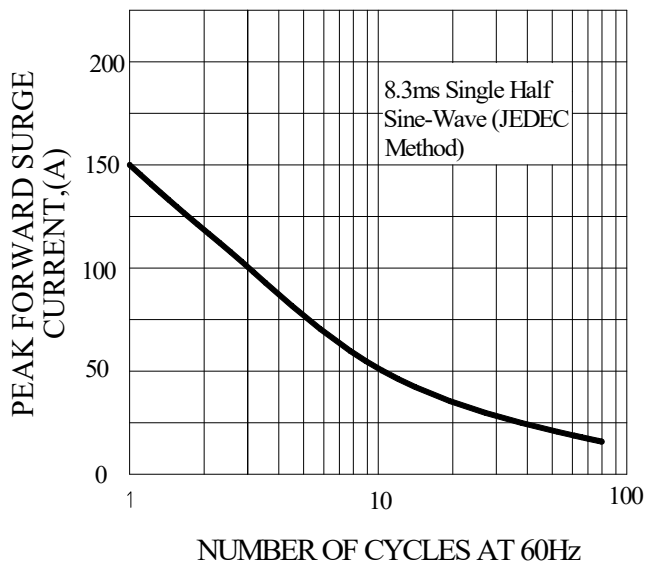
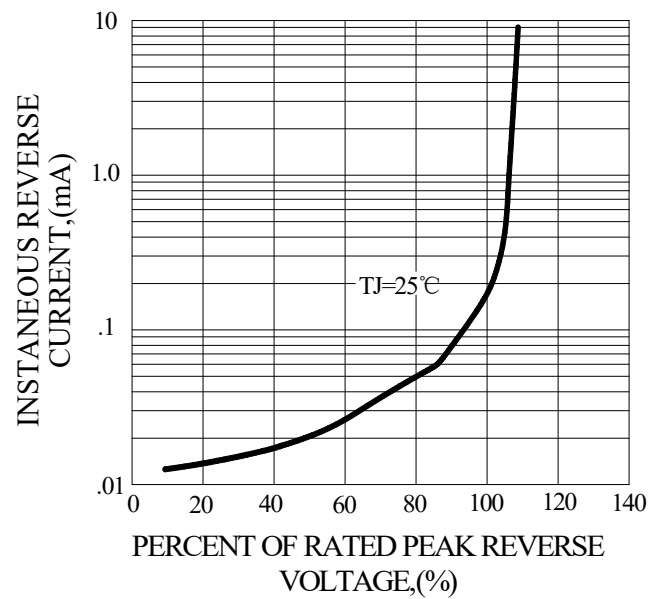
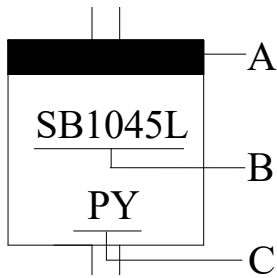


FIG.4-TYPICAL REVERSE CHARACTERISTICS



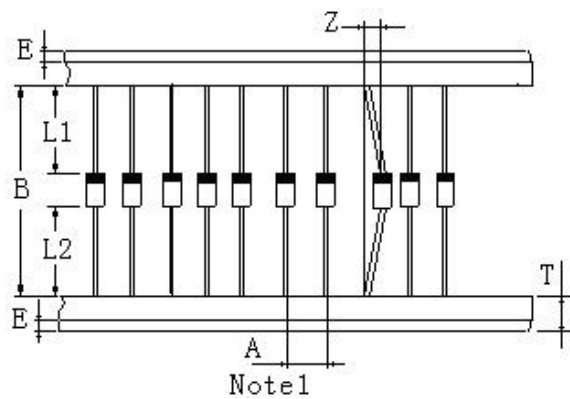
## Marking、 bending and packaging illustration

### 1、 Marking



SYMBOL	Explanation
<b>A</b>	<b>Color Band Denotes Cathode</b>
<b>B</b>	<b>Product Name</b>
<b>C</b>	<b>Trademark</b>

### 2、 Packaging



ITEM	SYMBOL	SPECIFICATIONS (mm)	SPECIFICATIONS (inch)
Component alignment	Z	1.2max	0.048max
Tape width	T	6.0±0.4	0.236±0.016
Exposed adhesive	E	0.8max	0.032max
Body eccentricity	L1-L2	1.0max	0.040max
Component	A	10.0±0.5	0.4±0.02
Inner tap	B	52.0~53.5	2.06~2.11
NOTE: Each component lead shall be sandwiched between tapes for a minimum of 2.5mm (0.1inch)			